

Positive Temperature Coefficient (PTC) Data Sheet

Description

The 0603 series provides miniature surface mount resettable overcurrent protection with holding current from 40mA to 500mA. This series is suitable for ultra portable applications where space is at a premium and the device current is low.



Features

- RoHS compliant and lead-free
- Halogen-free
- Compact design saves board space
- Low profile
- Fast response to fault current
- Compatible with high temperature solders

Applications

- Mobile phones and PDAs
- Portable MP3 and media player
- Mobile internet Device (MID)

- USB peripherals
- IC VCC protection

Agency Approval and Environmental Compliance

Agency	File Number
UL/CUL	E482628
TUV	B160696048001

Regulation	Standard
RoHS	2011/65/EU
Halogen Free	EN 14582:2007

Electrical Characteristics

Part	I _{hold}	l _{trip}	I _{trip} V _{max} (A) (Vdc)	V _{max} I _{max}	I _{max} P _{d typ.}	Maximum Time To Trip		Resistance						
Number	(A)	(A)		(Vdc)	(Vdc)	dc) (A)	(A)	(A)	(A)	(Vdc) (A)	(W)	Time (Sec.)	Current (A)	R _{min} (Ω)
SMD0603B004TF	0.04	0.12	24	20	0.5	1.00	0.20	4.000	40.000					
SMD0603B010TF	0.10	0.30	15	40	0.5	1.00	0.50	0.900	6.000					
SMD0603B020TF	0.20	0.50	9	40	0.5	0.60	1.00	0.550	3.500					
SMD0603B025TF	0.25	0.55	9	40	0.5	0.08	8.00	0.500	3.000					
SMD0603B035TF	0.35	0.75	6	40	0.5	0.10	8.00	0.200	1.000					
SMD0603B050TF	0.50	1.00	6	40	0.5	0.10	8.00	0.100	0.680					



Note on Electrical Characteristics

Vocabulary

- I_{hold} = Hold current: maximum current device will pass without tripping in 23℃ still air.
- I_{trip} = Trip current: minimum current at which the device will trip in 23°C still air.
- V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})
- I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})
- P_{d typ.} = Typical power dissipated from device when in the tripped state at 23°C still air.
- R_{min} = Minimum resistance of device in initial (un-soldered) state.
- R_{1max} = Maximum resistance of device at 23 ℃ measured one hour after tripping or reflow soldering of 260 ℃ for 20 sec.
- Value specified is determined by using the PWB with 0.020"*1.5oz copper traces.
- Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.
- Specifications are subject to change without notice.

Polymeric PTC Selecting Guide

- Determine the following operating parameters for the circuits:
 - Normal operating current (I_{hold})
- Maximum interrupt current (I_{max})
- Maximum circuit voltage (V_{max})
- Normal operating temperature surrounding device (min °C/max °C)
- Select the device from factor and dimension suitable for the application
- Compare the maximum rating for V_{max} and I_{max} of the PPTC device with the circuit in application and make sure the circuit's requirement does not exceed the device rating.
- Check that PPTC device's trip time (time-to-trip) will protect the circuit.
- Verify that the circuit operating temperature is within the PPTC device's normal operating temperature range.
- Verify that performance and suitability of the chosen PPTC device in the application.

A WARNING

Mechanical Stress

PPTC devices will undergo a thermal expansion during fault condition. If PPTC devices are installed or placed in an application
where the space between PPTC devices and the surrounding materials (e.g., covering materials, packaging materials, encapsulate
materials and the like) is insufficient, it will cause an inhibiting effect upon the thermal expansion. Pressing, twisting, bending and
other kinds of mechanical stress will also adversely affect the performance of the PPTC devices, and shall not be used or applied.

■ Chemical Pollutants

• Silicone-based oils, oils, solvents, gels, electrolytes, fuels, acids, and the like will adversely affect the properties of PPTC devices, and shall not be used or applied.

■ Electronic and Thermal Effect

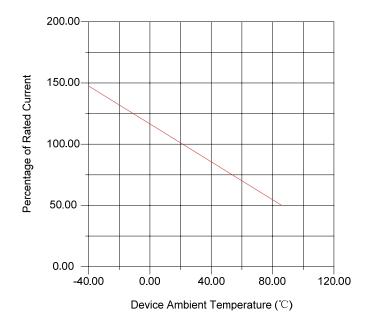
- PPTC devices are secondary protection devices and are used solely for sporadic, accidental over-current or over-temperature
 error condition, and shall NOT be used if or when constant or repeated fault conditions (such fault conditions may be caused by,
 among others, incorrect pin-connection of a connector) or over-extensive trip events may occur.
- PPTC devices are different from fuses and, when a fault condition occurs, will go into high-resistance state and do not open circuit, in which case the voltage at such PPTC devices may reach a hazardous level.
- Operation over the maximum rating or other forms of improper use may cause failure, arcing, flame and/or other damage to the PPTC devices.
- Conductive material contamination, such as metal particle, may induce shortage, flame or arcing.
- Due to the inductance, the operation circuits may generate a circuit voltage (Ldi/dt) above the rated voltage of PPTC devices, which shall not be used under such circumstances.

General

- Customers shall evaluate and test the properties of PPTC devices independently to verify and ensure that their individual applications will be met.
- The performance of PPTC devices will be adversely affected if they are improperly used under electronic, thermal and/or mechanical procedures and/or conditions non-conformant to those recommended by manufacturer.
- Customers shall be responsible for determining whether it is necessary to have back-up, failsafe and/or fool-proof protection To avoid or minimize damage that may result from extra-ordinary, irregular function or failure of PPTC devices.
- · Any and all responsibilities and liabilities are disclaimed if any item under this notice of warning is not complied with.



Thermal Derating Curve

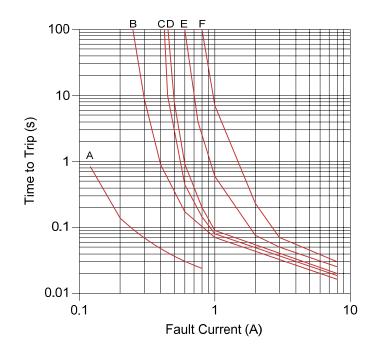


Thermal Derating Chart

Recommended Hold Current (A) at Ambient Temperature ($^{\circ}$ C)

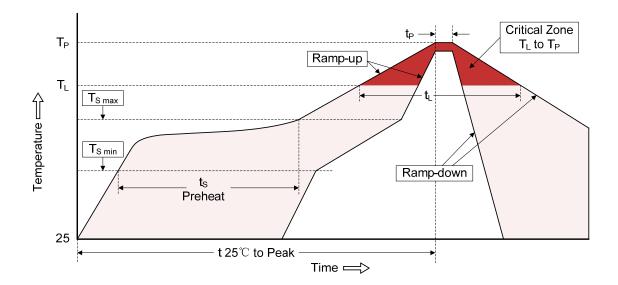
Part		Ambient Operation Temperature							
Number	-40℃	-20℃	0℃	23℃	40℃	50 ℃	60℃	70 ℃	85℃
SMD0603B004TF	0.052	0.048	0.044	0.040	0.032	0.028	0.024	0.020	0.012
SMD0603B010TF	0.13	0.12	0.11	0.10	0.08	0.07	0.06	0.05	0.03
SMD0603B020TF	0.27	0.25	0.23	0.20	0.17	0.14	0.12	0.10	0.07
SMD0603B025TF	0.32	0.29	0.27	0.25	0.21	0.18	0.16	0.14	0.10
SMD0603B035TF	0.47	0.41	0.38	0.35	0.29	0.26	0.24	0.20	0.14
SMD0603B050TF	0.67	0.59	0.54	0.50	0.41	0.37	0.34	0.29	0.20

Average Time-Current Curve



A-SMD0603B004TF B-SMD0603B010TF C-SMD0603B020TF D-SMD0603B025TF E-SMD0603B035TF F-SMD0603B050TF

Soldering Parameters



Profile Feature	Pb-Free Assembly
Average ramp-up rate (T _{S max} to T _P)	3°C/second max.
Preheat -Temperature Min (T_{Smin}) -Temperature Max (T_{Smax}) -Time (min to max) $(T_{Smin}$ to $T_{Smax})$	150℃ 200℃ 60-180 seconds
Time maintained above: -Temperature (T_L) -Time (t_L)	217℃ 60-150 seconds
Peak Temperature (T _P)	260℃
Time within 5℃ of actual Peak Temperature (t _P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25℃ to Peak Temperature	8 minutes max.
Storage Condition	0°C~35°C, ≤70%RH

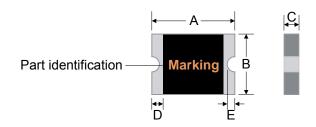
- Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free
- Recommended maximum paste thickness is 0.25mm (0.010 inch)
- Device can be cleaned using standard industry methods and solvents.

Note 1: All temperature refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.



Physical Dimensions (mm)



Part	ı	Ą	E	3	(C	[)	E	≣
Number	Min.	Max.								
SMD0603B004TF	1.40	1.80	0.60	1.00	0.40	1.00	0.15	0.50	-	0.40
SMD0603B010TF	1.40	1.80	0.60	1.00	0.40	1.00	0.15	0.50	-	0.40
SMD0603B020TF	1.40	1.80	0.60	1.00	0.40	1.00	0.15	0.50	-	0.40
SMD0603B025TF	1.40	1.80	0.60	1.00	0.40	1.00	0.15	0.50	-	0.40
SMD0603B035TF	1.40	1.80	0.60	1.00	0.55	1.55	0.15	0.50	-	0.40
SMD0603B050TF	1.40	1.80	0.60	1.00	0.55	1.55	0.15	0.50	-	0.40

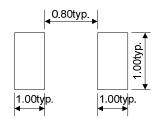
Environmental Specifications

Operating / Storage temperature	-40°C to +85°C			
Maximum Device Surface Temperature in Tripped State	125℃			
Passive Aging	+85℃, 1000 hours			
1 assive Aging	±50% typical resistance change			
Humidity Aging	+85℃, 85%R.H. 1000 hours			
Trumbuty Aging	±50% typical resistance change			
	MIL-STD-202, Method 107G			
Thermal Shock	+85℃/-40℃ 20 times			
	-50% typical resistance change			
Coluent Desistance	MIL-STD-202, Method 215			
Solvent Resistance	No change			
Vibration	MIL-STD-883C, Method 2007.1, Condition A			
VIDIALIOIT	No change			
Moisture Level Sensitivity	Level 1, J-STD-020C			



Packaging Quantity and Marking

Recommended Pad Layout (mm)



Part Number	Marking	Quantity
SMD0603B004TF	_	4000
SMD0603B010TF	С	4000
SMD0603B020TF	Н	4000
SMD0603B025TF	I	4000
SMD0603B035TF	F	4000
SMD0603B050TF	J	4000

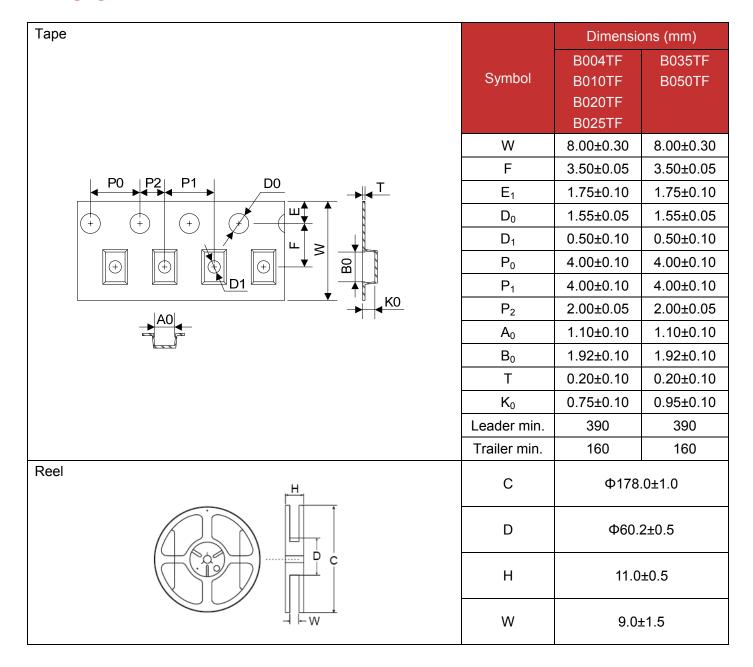
^{© 8}mm tape on 7 inch reel per EIA-481 (equivalent to IEC286, part 3)

Physical Specifications

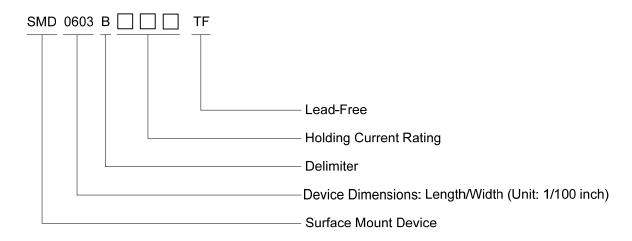
Terminal Material	Solder-Plated Copper (Solder Material: Matte Tin (Sn))
Lead Solderability	Meets EIA Specification RS186-9E, ANSI/J-STD-002 Category 3.



Packaging



Part Number System



X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Resettable Fuses - PPTC category:

Click to view products by Yageo manufacturer:

Other Similar products are found below:

RF0077-000 RF3256-000 RF3281-000 RF3301-000 RF3341-000 RF3344-000 RF3382-000 SMD125-2 RF2171-000 RF2531-000 RF2873-000 RF3060-000 TR600-150Q-B-0.5-0.130 RXE090 5E4795/04-1502 TRF250-080T-B-1.0-0.125 SMD100-2 NIS5452MT1TXG

NIS5431MT1TXG SMD250-2 0ZCM0001FF2G 0ZCM0003FF2G 0ZCM0004FF2G BK60-017-DZ-E0.6 F95456-000 LVR100S RS30-090 RS30-110 RS30-600 RS30-700 RS30-800 RS30-900 RS60RB-005 RS60RB-010 RS60RB-020 RS60RB-025 RS60RB-050 RS60RB-075 RS60RB-160 RS60SB-250 ASMD0603-010-30V ASMD0603-025-16V ASMD2920-260-24V BSMD0603-025-12V BSMD1206-150-12V BSMD0805-020-33V BSMD1206-075-13.2V BSMD2920-400-6V BSMD2920-300-6V BSMD2920-700-6V